

Abstract of the Disclosure

The present invention is an optical waveguide module having e.g., a high impact resisting property and a high vibration resisting property. An optical waveguide circuit chip is supported by at least a peripheral portion of an edge portion and is stored into a storing portion of a package. The optical waveguide chip is formed by arranging an optical waveguide forming area on a substrate. An elastic member for impact relaxation of the optical waveguide circuit chip is arranged in at least one portion of the vicinity of the edge portion of the optical waveguide circuit chip. For example, the elastic member is arranged in the vicinity of each of four corners of the optical waveguide circuit chip.